### Nch 600V 11A Power MOSFET

V <sub>DSS</sub>	600V
R <sub>DS(on)</sub> (Max.)	0.39Ω
I <sub>D</sub>	±11A
P <sub>D</sub>	53W

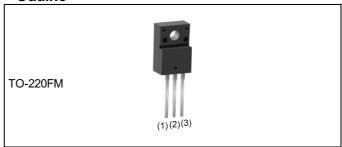
### Features

- 1) Low on-resistance
- 2) Fast switching
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free plating; RoHS compliant

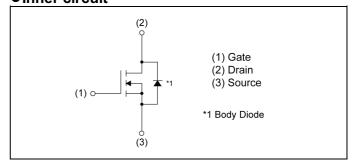
## Application

Switching

## Outline



## ●Inner circuit



Packaging specifications

Code	Packing
C7 G	Tube
C7	Tube*
- (Blank)	Bulk*

<sup>\*</sup>Package dimensions are different

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	$V_{DSS}$	600	V	
Continuous drain current	I <sub>D</sub> *1	±11	Α	
Pulsed drain current	I <sub>DP</sub> *2	±22	Α	
static		V	±20	V
Gate - Source voltage	AC(f>1Hz)	$V_{GSS}$	±30	V
Avalanche current, repetitive		I <sub>AS</sub>	1.8	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	210	mJ
Avalanche energy, repetitive		E <sub>AS</sub> *3	0.32	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	53	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage tempera	ature range	T <sub>stg</sub>	-55 to +150	°C

# ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values	Unit
Reverse diode dv/dt	dv/dt	-	15	V/ns
Drain - Source voltage slope	dv/dt	$V_{DS} = 480V, T_j = 25^{\circ}C$	50	V/ns

## ●Thermal resistance

Doromotor	Cumb of	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	2.4	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	70	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	1	-	265	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r al al lietel	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 1mA$	600	-	-	V
		V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	T <sub>j</sub> = 25°C	-	0.1	100	μΑ
drain ourione		T <sub>j</sub> = 125°C	-	1	1000	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	2	-	4	V
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.8A				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	T <sub>j</sub> = 25°C	-	0.34	0.39	Ω
on state resistance		T <sub>j</sub> = 125°C	-	0.72	-	
Gate resistance	R <sub>G</sub>	f =1MHz, open drain	-	7.7	-	Ω

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanatav	Cymah al	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 10V, I <sub>D</sub> = 5.5A	3.0	6.0	-	S
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	670	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	570	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	70	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	V <sub>GS</sub> = 0V	-	30	-	<u>ا</u>
Effective output capacitance, time related	C <sub>o(tr)</sub>	$V_{DS} = 0V \text{ to } 480V$	-	136	-	pF
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≃ 300V,V <sub>GS</sub> = 10V	-	25	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 5.5A	-	40	-	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ≃ 54.9Ω	-	90	-	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	35	-	

## ● Gate charge characteristics (T<sub>a</sub> = 25°C)

( 'a )						
Parameter	Cumbal	Conditions	Values			1.1-:4
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 300V,	-	32	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 11A,	-	5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	17	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> = 300V, I <sub>D</sub> = 11A	-	6.0	-	V

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

<sup>\*3</sup> L $\doteqdot$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>j</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Pulsed

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Cumb ol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offit
Continuous forward current	I <sub>S</sub> *1	T - 25°C	-	-	11	А
Pulse forward current	I <sub>SP</sub> *2	T <sub>C</sub> = 25°C	-	-	22	А
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 11A	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *5		-	430	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	$I_S = 11A$ di/dt = 100A/µs	-	4.5	-	μC
Peak reverse recovery current	I <sub>rrm</sub> *5	αναι 100/4μ3	-	22	-	Α

## Typical transient thermal characteristics

Symbol	Value	Unit
R <sub>th1</sub>	0.261	
R <sub>th2</sub>	0.973	K/W
R <sub>th3</sub>	2.18	

Symbol	Value	Unit
C <sub>th1</sub>	0.00167	
C <sub>th2</sub>	0.0192	Ws/K
C <sub>th3</sub>	0.460	

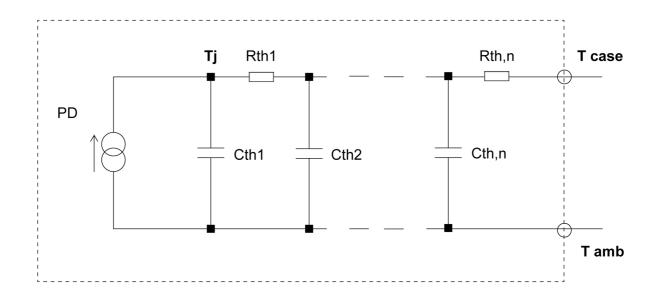


Fig.1 Power Dissipation Derating Curve

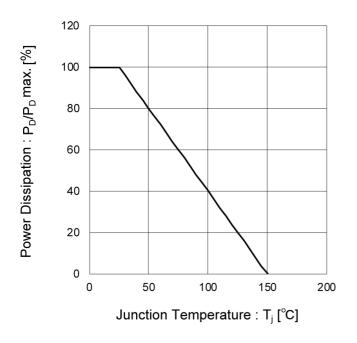


Fig.2 Drain Current Derating Curve

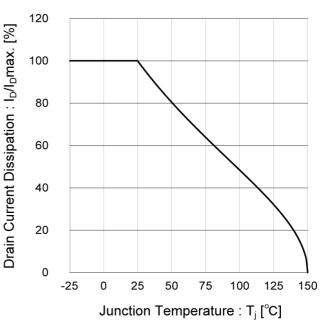


Fig.3 Normalized Transien Thermal Resistance vs. Pulse Width

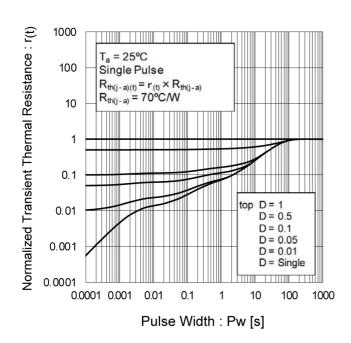
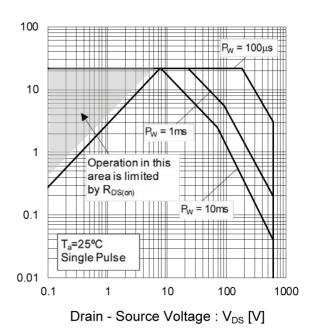


Fig.4 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Fig.5 Avalanche Energy Drating Curve vs. Junction Tempreture

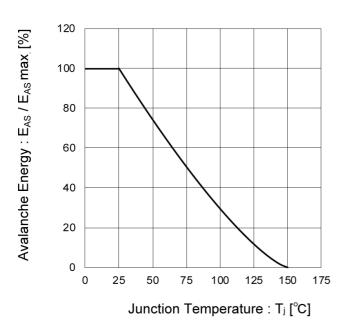


Fig.6 Breakdown Voltage vs. Junction Temperature

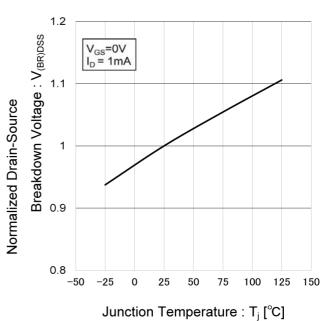


Fig.7 Typical Output Characteristics(I)

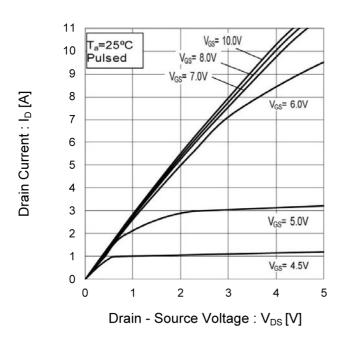
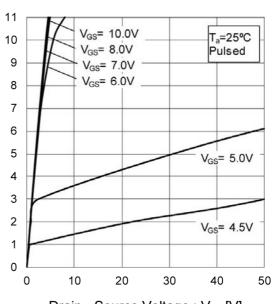


Fig.8 Typical Output Characteristics(II)



 $Drain - Source\ Voltage: V_{DS}[V]$ 

Drain Current : I<sub>D</sub> [A]

Fig.9 Typical Transfer Characteristics

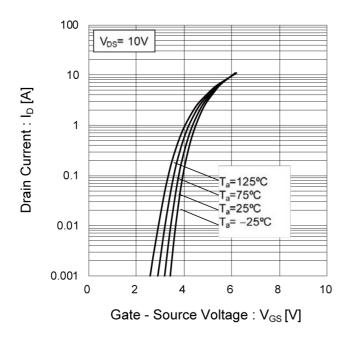


Fig.10 Gate Threshold Voltage vs.
Junction Temperature

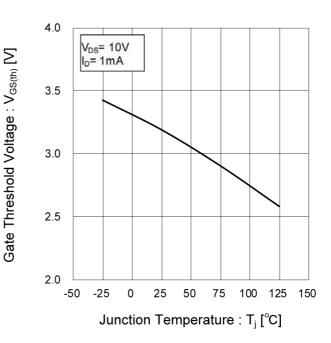


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

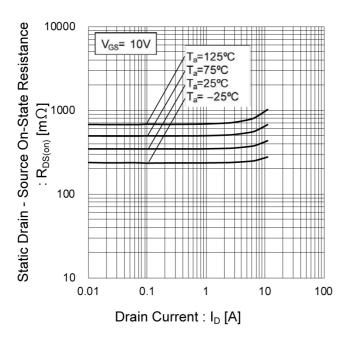


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

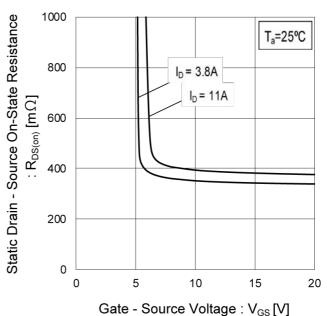


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

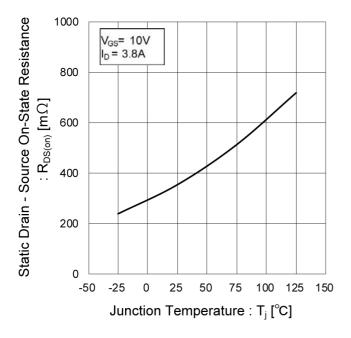


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

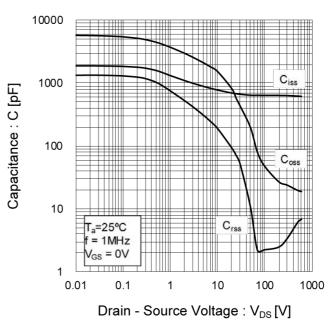


Fig.15 Switching Characteristics

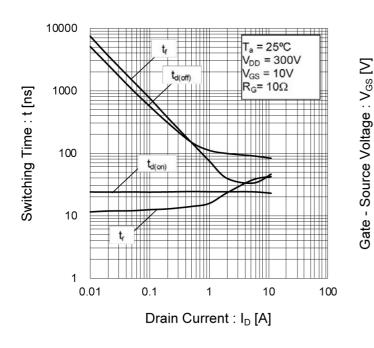


Fig.16 Typical Gate Charge

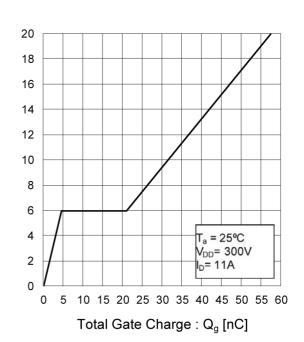


Fig.17 Source Current vs. Source - Drain Voltage

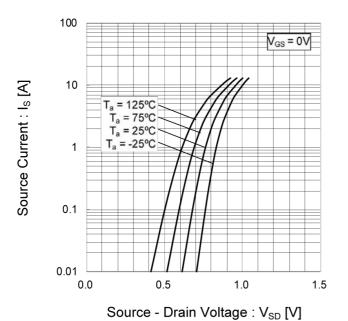
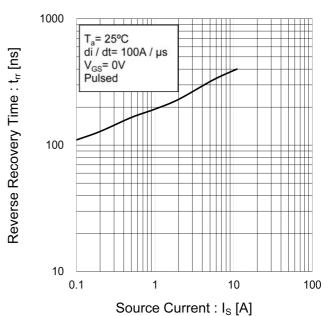


Fig.18 Reverse Recovery Time vs. Source Current



ROHM

#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

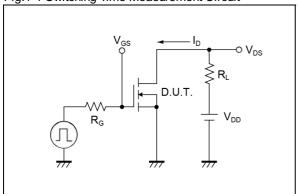


Fig.2-1 Gate Charge Measurement Circuit

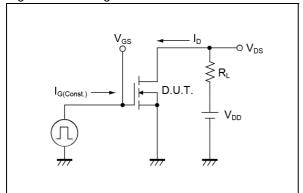


Fig.3-1 Avalanche Measurement Circuit

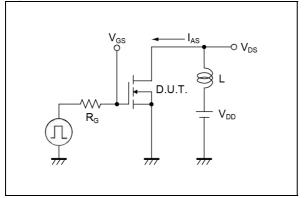


Fig.4-1 trr Measurement Circuit

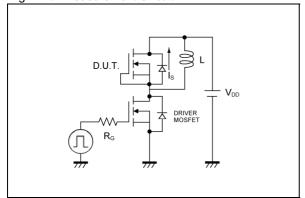


Fig.1-2 Switching Waveforms

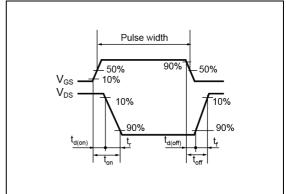


Fig.2-2 Gate Charge Waveform

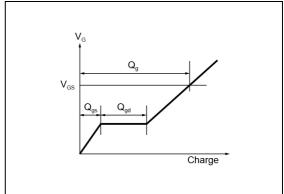


Fig.3-2 Avalanche Waveform

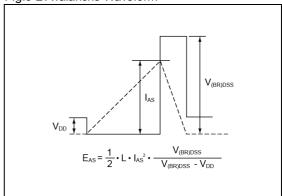
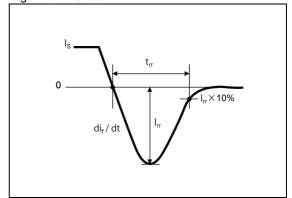
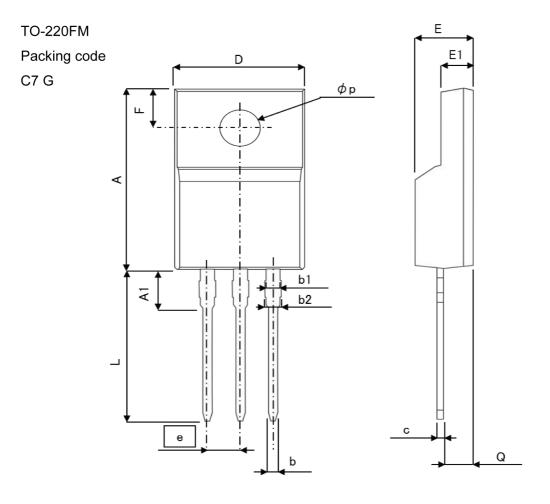


Fig.4-2 trr Waveform



## Dimensions

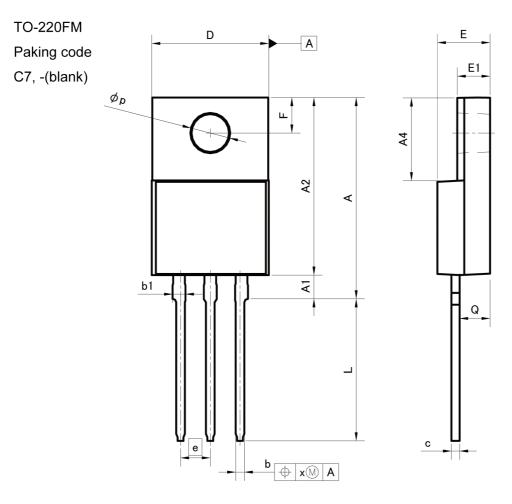


DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	15.67	16.27	0.617	0.641
A1	3.03	3.43	0.119	0.135
b	0.70	0.95	0.028	0.037
b1	1.00	1.40	0.039	0.055
b2	1.10	1.50	0.043	0.059
С	0.45	0.65	0.018	0.026
D	9.90	10.30	0.390	0.406
Е	4.60	5.00	0.181	0.197
E1	2.44	2.74	0.096	0.108
е	2.	54	0.100	
F	3.10	3.50	0.122	0.138
L	12.6	13.6	0.946	0.535
р	2.98	3.38	0.117	0.133
Q	2.25	3.25	0.089	0.128

Dimension in mm/inches



## Dimensions



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.90	0.028	0.035
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
E	4.40	4.80	0.173	0.189
е	2.54		0.100	
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
×	-	0.38	-	0.015

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSⅢ
CLASSIV	CLASSIII	CLASSⅢ	

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
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- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Rev.001

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